

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



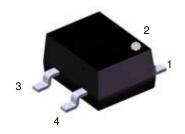






DATASHEET

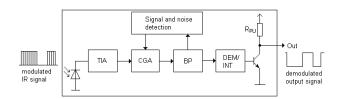
Infrared Remote Control Receiver Module EAIRMKA1 & EAIRMKA2



Pin Configuration

- 1. GND 2. GND
- 2. GND 3. OUT
- 4. Vcc

Block Diagram



Features

- · High protection ability against EMI
- · Available for various carrier frequencies
- · Min burst length: 10 cycles
- · Min gap length: 14 cycles
- · Low operating voltage and low power consumption
- · High immunity against ambient light
- · Long reception range
- · High sensitivity
- · Pb free and RoHS compliant
- · Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Descriptions

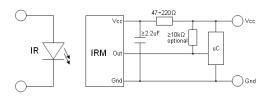
- The device is miniature SMD type infrared receiver that has been developed and designed by utilizing the latest IC technology.
- The PIN diode and preamplifier are assembled onto a lead frame and molded into a black epoxy package which operates as an IR filter. The demodulated output signal can directly be decoded by a microprocessor

Applications

- · Light detecting portion of remote control
- · AV instruments such as Audio, TV, VCR, CD, MD, etc
- · Home appliances such as Air-conditioner, Fan, etc
- · 0ther devices using IR remote control
- · CATV set top boxes
- · Multi-media Equipment



Application Circuit



RC Filter should be connected closely between Vcc pin and GND pin.

Parts Table

Model No.	Carrier Frequency		
EAIRMKA1	36 kHz		
EAIRMKA2	38 kHz		

Absolute Maximum Ratings (T_a=25°C)

Parameter	Symbol	Rating	Unit
Supply Voltage	Vs	6	V
Operating Temperature	Topr	-20 ~ +80	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	-40 ~ +85	$^{\circ}\mathbb{C}$
Soldering Temperature *1	Tsol	260	$^{\circ}$ C

 $^{^{\}star 1}$ 4mm from mold body less than 5 seconds



Electro-Optical Characteristics (Ta=25°C and Vcc=3.0V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Current Consumption	lcc	-	0.4	0.6	mA	No signal input
Supply Voltage	Vs	2.7	-	5.5	V	
Peak Wavelength	λ_{p}	-	940	-	nm	
	L ₀	8	-	-	_ m	See chapter ,Test method'
Reception Distance	L ₄₅	5	-	-		
Half Angle (Horizontal)	Θ_{h}	-	45	-	deg	
Half Angle (Vertical)	Θ_{v}	-	45	-	deg	
High Level Pulse Width	T_WH	450	-	750	μs	Test signal according
Low Level Pulse Width	T _{WL}	450	-	750	μs	to figure 1
High Level Output Voltage	V_{H}	Vcc-0.4	-	-	V	
Low Level Output Voltage	V _L	-	0.2	0.5	V	I _{SINK} ≦2mA
Internal pull up resistor	R_{PU}	85	100	115	kΩ	



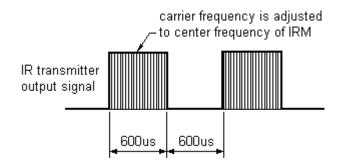
Test Method

The specified electro-optical characteristic is satisfied under the following Conditions:

- 1. Measurement environment
 - A place without extreme light reflected
- 2. External light
 - Ordinary white fluorescent lamps (Light source temperature 2856°K, Ee ≤ 10Lux) without high frequency modulation
- 3. Standard transmitter
 - The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until **Vo=400mVp-p.** Both, the test transmitter and the photo diode, have a peak wavelength of 940nm. The photo diode for calibration is PD438B (λp=940nm, Vr=5V).
- 4. Measuring system According to the measuring system shown in Fig.-3

Fig.-1 Transmitter Wave Form

D.U.T output Pulse



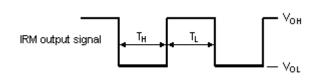


Fig.-2 Measuring Method

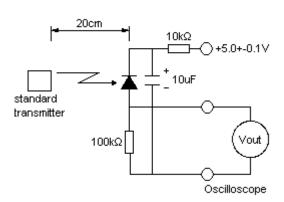
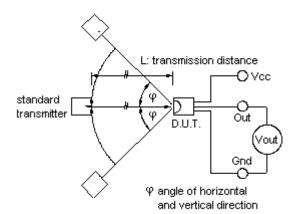


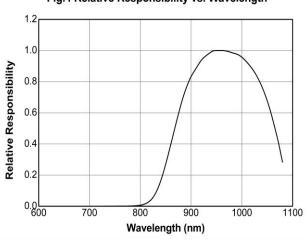
Fig.-3 Measuring System





Typical Performance Curves

Fig.4 Relative Responsibility vs. Wavelength



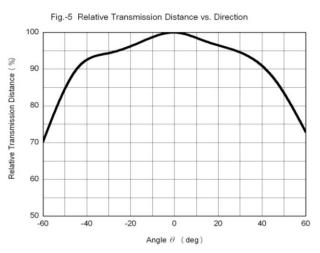


Fig.6 Variation Output Pulse Width vs. Distance

150 100 100 50 50 -50 -150 2 4 6 8 10 12 14 Distance (m)

Fig.7 Relative Sensitivity vs. Supply Voltage

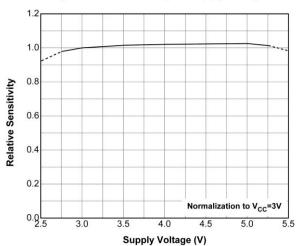
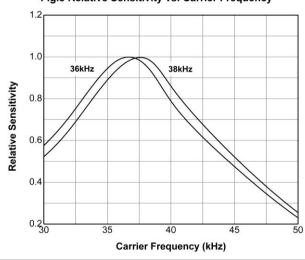


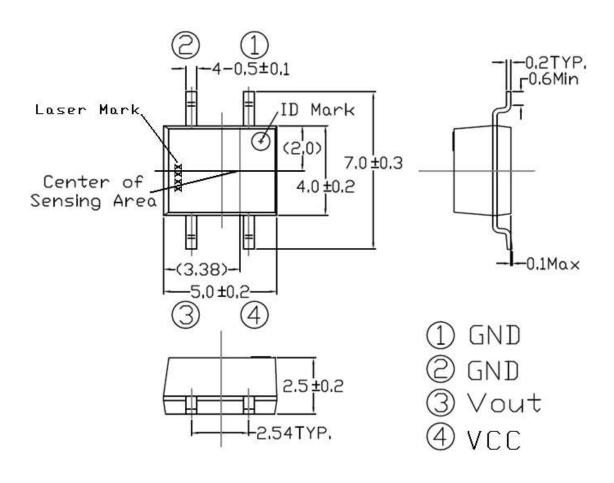
Fig.8 Relative Sensitivity vs. Carrier Frequency



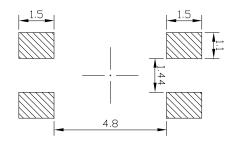


Package Dimenstions

(Dimensions in mm)



Recommended pad layout for surface mount leadform

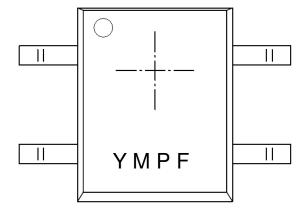




Code information

Protocol	Suitable	Protocol	Suitable
JVC	Yes	RCA	No
Matsushita	Yes	Sharp	Yes
Mitsubishi	No	Sony 12 Bit	Yes
NEC	Yes	Sony 15 Bit	No
RC5	Yes	Sony 20 Bit	No
RC6	Yes	Toshiba	Yes
RCMM	No	XMP-1	Yes
RCS-80	No	Continuous Code	No

Device Marking

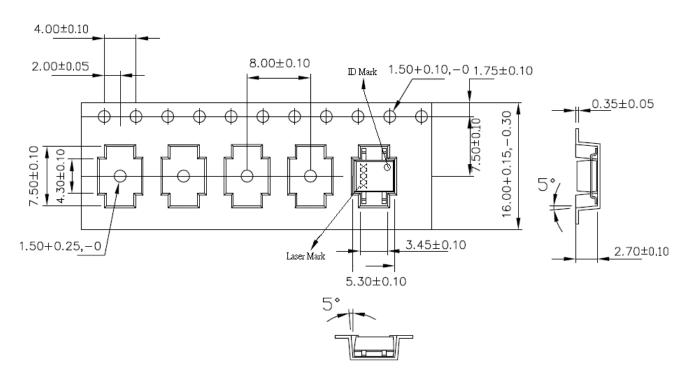


Notes

- Y denotes Years code
- M denotes Month code
- P denotes Device number
- F denotes Carrier frequency (2: 36KHz, 4: 38KHz)



Tape & Reel Packing Specifications



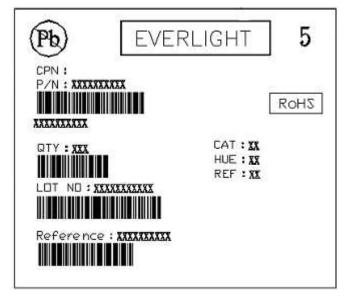
Packing Quantity

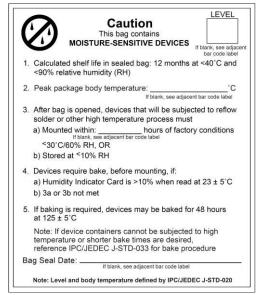
1000 pcs / Reel

5 Reels / Carton



Label format





Moisture Classification-storage and used condition label

Recommended method of storage

The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

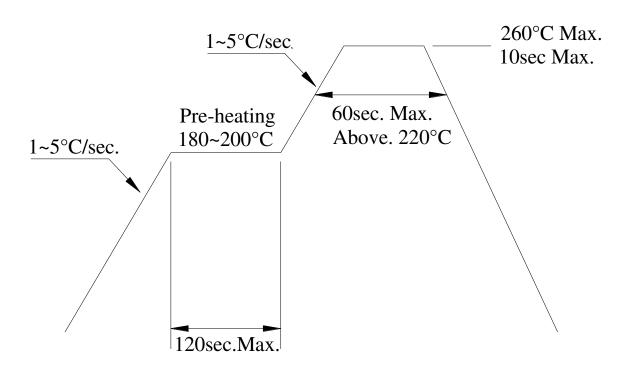
- 1. Shelf life in sealed bag from the bag seal date: 12 months at < 40 °C and < 90% relative humidity (RH)
- 2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must mounted within 72 hours of factory conditions < 30 °C/60%RH.
- 3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions: 60±5°C for 96 hours.

ESD Precaution

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.



Solder Reflow Temperature Profile



Note:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the IRM device during heating.
- 3. After soldering, do not warp the circuit board.

DISCLAIMER

- 1. Everlight Americas will reserve the right to make changes on specification and material but with notice.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of Everlight Americas. Reproduction in any form is prohibited without the specific consent of Everlight Americas.